

GENE-A55E

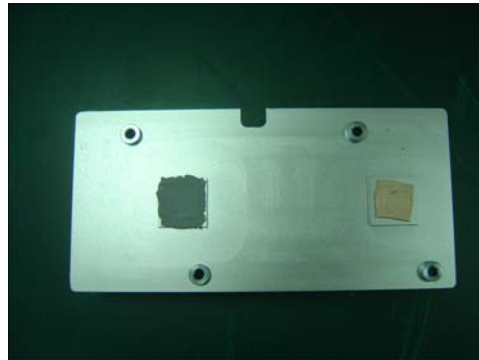
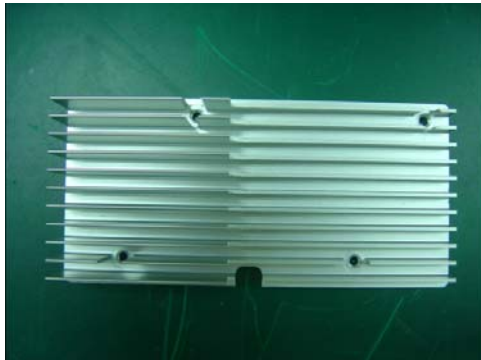
Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>Temperature at 1 component was estimated to be in marginal temperature point in comparison with component datasheet.</u> <u>There are 1 component in the absence of Tc and Tj specification, So we are unable to determine.</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	2
Defect Unsolved	0	0	0	2

Issue date	QE Manager	Test Engineer
2016 / 11 /11	KJ Wang	Juno Cheng

Sample Configuration & Quantity Under Test

- **Model name : GENE-A55E Rev.A1.1**
- **CPU : AMD T46N**
- **Chipset : AMD-A55E**
- **Memory : Transcend DDR3L 1600 SODIMM 4GB/ SEC K4B4G0846D**
- **2.5" HDD : FUJITSU MHW2040BH X 40 GB**
- **BIOS : R1.6 (GA5EAM16) (02/18/2016)**
- **Test Software : Windows 7 / Run Run BurnIn test 8.1**
- **AT Power : HGZ-6400P**
- **Heat Sink (M16A55E020) :**



Thermal Image Analysis

1. Test Date: 2016-11-11

2. Test Product: GENE-A55E

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 YOKOGAWA Inc,

4.2.2 Model: DA100-13-1D

Date of Calibration: 2016/09/10

Serial Number: 12A323190

4.2. IR Scanner: Infrared Camera

4.2.1 NEC Avio Infrared Technologies Co., Ltd.

4.2.2 Model: Thermo GEAR G100W2-D

Date of Calibration: 2016/12/01

Serial Number: 1051444

5. Test Condition:

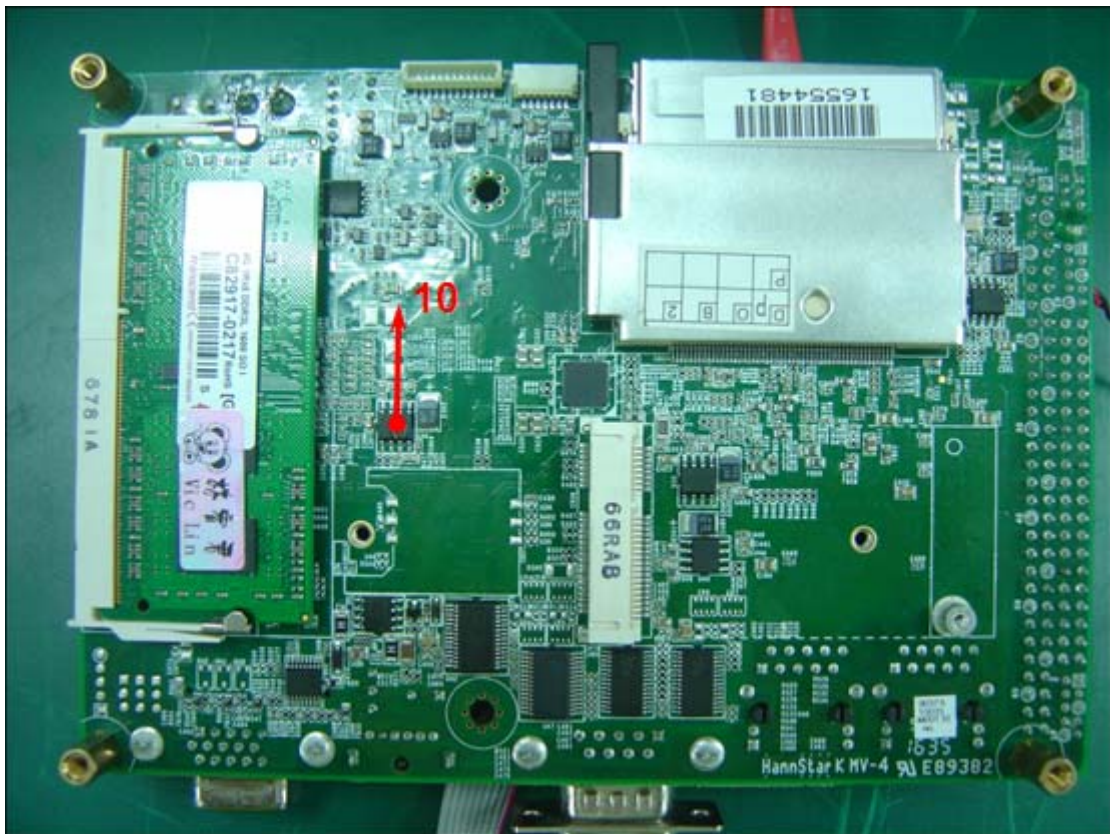
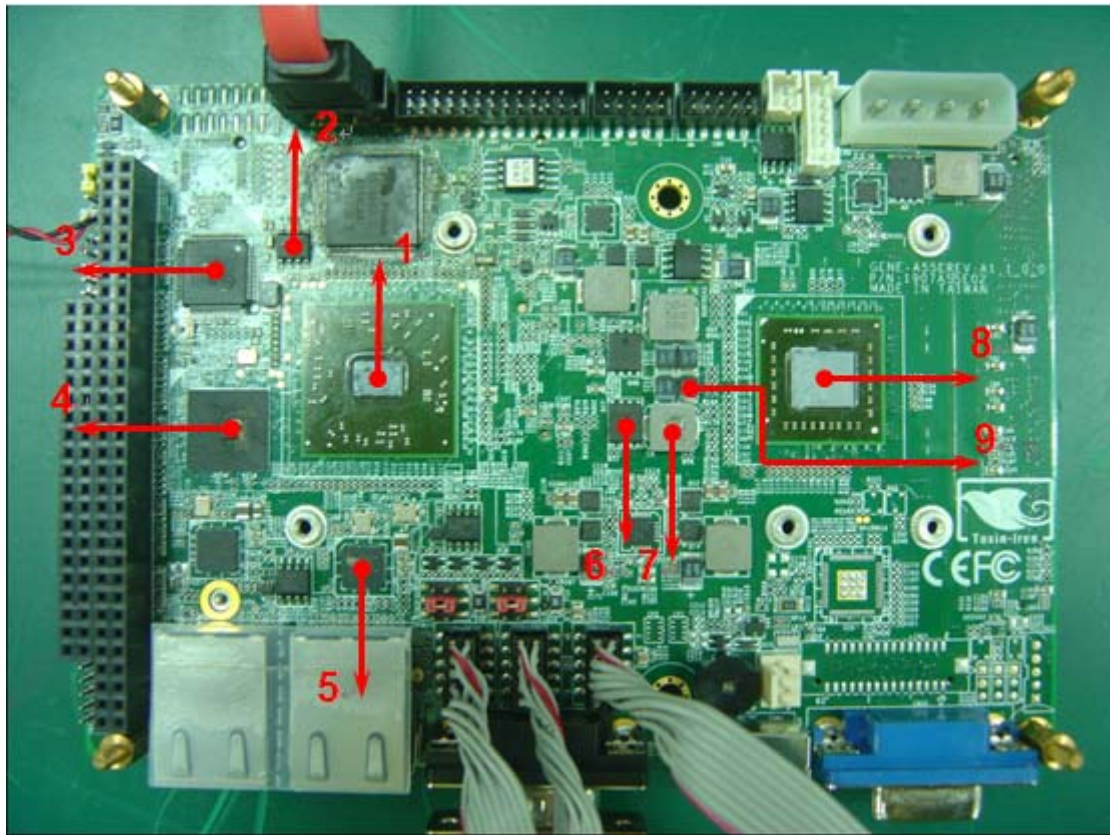
Test by DA-100: 23.0°C with CPU Cooler

6. Take Picture Time:

After power on 2 hours

Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)	TPT(*3)	Note
				25.0°C	60°C	
1	U13	(TF) CPU AMD.T46R	100	54.8	89.8	
2	U10	(TF)IC.RICHTEK.RT9025-25PSP	100	53.7	88.7	
3	U12	(TF)IC.SATA to IDE/ATA.Jmicron.JMD330-TGAA1D	100	54.1	89.1	
4	U16	(TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G-L	NA	50.9	85.9	Note 6
5	U23	(TF)IC.REALTEK.RTL8111E-VL-CG	100	50.3	85.3	
6	Q37	(TF)PWR.DUALSMD. PQFN8.FAIRCHILD.FDMS3664S	125	52.5	87.5	
7	L9	(TF)COIL. CYNTEC.PCMB063T-1R0MS	140	52.7	87.7	
8	U14	(TF)AMD.FCBGA 413P.GET56NGBB22GVE.T56N	90	52.3	87.3	Note 4
9	C542	(TF)CAP. NEC-TOKIN.TEPSGB20E337M9-8R	120	51.8	86.8	
10	U34	(TF)IC.LDO Linear Regulator. SMD.RICHTEK.RT9025-25PSP	100	56.9	91.9	
11		DIMM	95	46.3	81.3	

Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "TAT" indicates the actual measured temperature under product specification.
3. "TPT" indicates the predicted temperature under 25°C working environmental.
4. **Judgment Criteria:**
 - **Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
 - **Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.
5. **RTC battery avoid to put on heat position.** Please do not exceed battery temperature specification.
6. **Defect NO. :** [BUL1513LABD01](#)